

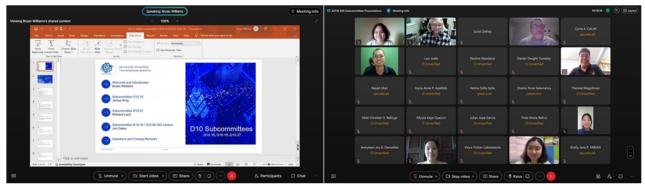
OVERVIEW

Throughout the second semester, the ASTM-CPU Student Chapter actively participated in five informative subcommittee presentation series, each designed to elevate our understanding and appreciation of ASTM standards and the ASTM Organization itself. These presentations played a critical role in helping us recognize the relevance and importance of these standards, especially in the context of Packaging Engineering. By exploring real-world applications and engaging with technical content, we were able to deepen our knowledge and gain valuable insights that are essential for our growth as future Packaging Engineering professionals in the field.

EVENTS

ASTM Series 1 Subcommittee Presentations

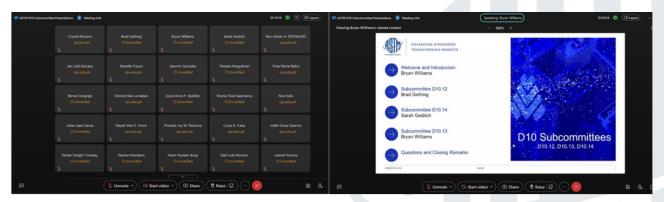
February 22, 2025, 7:00 PM (UTC-5) / February 22, 2025, 8:00 AM (UTC+8)



ASTM Series 1 Subcommittee Presentations featuring: **Richard Lund**, Chair of ASTM D10.27 on Corrugated Packaging; **James King**, leader at the Institute of Sales Professionals; **Bryan Williams**, Chair of the ASTM D10 Committee on Packaging; and **Jan Gates**, member of the IOPP HealthPack Advisory Board.

ASTM Series 2 Subcommittee Presentations

February 28, 2025, 7:00 AM (UTC-5) / February 28, 2025, 8:00 PM (UTC+8)



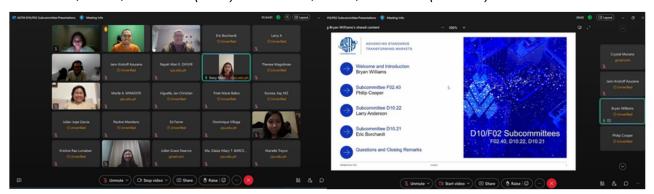




ASTM Series 2 Subcommittee Presentations featuring: **Bryan Williams**, Chair of the ASTM D10 Committee on Packaging; **Dr. Brad Gething**, the Vice President of National Wooden Pallet & Container Association (NWPCA); and **Sarah Gedrich**, second vice-chair of ASTM Committee D10.

ASTM Series 3 Subcommittee Presentations

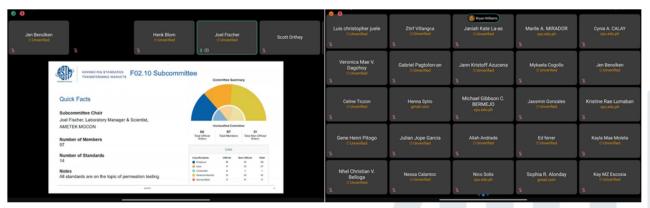
March 14, 2025, 8:00 AM (EST) / March 14, 2025, 8:00 PM (UTC+8)



ASTM Series 3 Subcommittee Presentations featuring: **Bryan Williams**, Chair of the ASTM D10 Committee on Packaging; **Philip Cooper**, Chair of ASTM Committee F2.40 Package Integrity; **Larry Anderson**, Chair of ASTM Committee D20.22 Cellular Materials-Plastics and Elastomers; along with **Eric Borchardt**, First Vice Chair of ASTM D10 Committee.

ASTM Series 4 Subcommittee Presentations

March 25, 2025, 7:00 AM (UTC-5) / March 25, 2025, 8:00 PM (UTC+8)

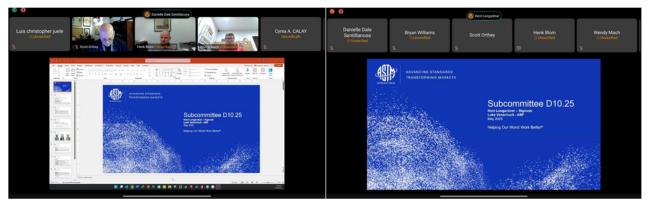


ASTM Series 4 Subcommittee Presentations featuring: **Henk Blom**, Chair of the F02 Committee; **Dan Burgess**, Chair of Subcommittee F02.25 on Rigid Container Closure Systems; **Joel Fischer**, Chair of Subcommittee F02.10 on Permeation; and **Jen Benolken**, Chair of Subcommittee F02.50 on Package Design and Development.



ASTM Series 5 Subcommittee Presentations

May 23, 2025, 8:00 AM (EST) / May 23, 2025, 8:00 PM (UTC+8)



ASTM Series 5 Subcommittee Presentations featuring: **Henk Blom** and **Logan Luke** for F02.30 Subcommittee on Mechanical Dispensers; **Wendy Mach** and **Meghan Supple**, presenting F02.15 Subcommittee on Chemical Safety and Properties; and **Travis Erickson** to present F02.20 Subcommittee on Physical Properties.

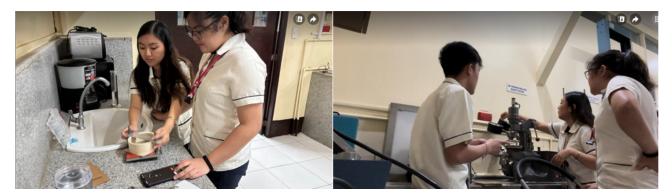
APPLICATIONS

In our program, ASTM standards are applied in nearly all laboratory activities and experiments. Courses with lab components—such as Polymer Packaging, Paper Packaging, Package and Materials Testing, Packaging Dynamics and Protective Design, and Transport Packaging, incorporate the actual ASTM standards into the hands-on learning experience. Some of the tests conducted in the laboratory following ASTM protocols include: Tensile and Elongation Testing, Vibration Testing, Cobb Test, Burst Test, Dimensional Testing, Torque Test, Leak Testing using Bubble Emission, Falling Dart Impact Test, Bending Stiffness Test, and the Ink Rub Test. These practical applications of ASTM standards reinforces technical accuracy and prepare students for real-world industry practices.





Cobb Test (left) and Burst Test (right)



Standards used: ASTM D3285 Standard Test Method for Water Absorptiveness of Nonbibulous Paper and Paperboard (Cobb Test) and ASTM D3786 Standard Test Method for Bursting Strength of Textile Fabrics—Diaphragm Bursting Strength Tester Method (Burst Test)

Torque Test (left) and Falling Dart Test (right)



Standards used: ASTM D3198 Standard Test Method for Application and Removal Torque of Threaded or Lug-Style Closures and ASTM D1709 Impact Resistance of Plastic Film by the Free-Falling Dart Method

Bending Stiffness Test



Standards used: ASTM D5342 Standard Test Method for Resistance to Bending of Paper and Paperboard





Tear Test



Standards used: ASTM D3689 Internal Tearing Resistance of Paper

Sutherland Ink Rub Test



Standards used: ASTM D5264 Standard Practice for Abrasion Resistance of Printed Materials by the Sutherland Rub Tester

Leak Test by Bubble Emission



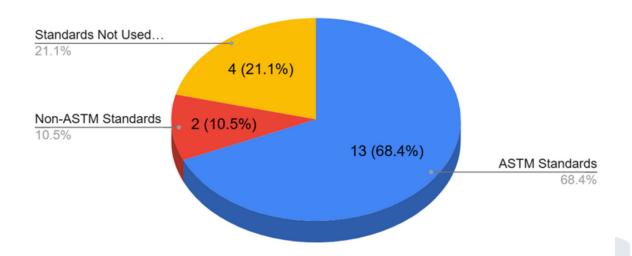
Standards used: ASTM D3078 – Standard Test Method for Determination of Leaks in Flexible Packaging by Bubble Emission



SUMMARY OF STANDARDS USAGE

The pie chart below visually represents the usage of standards in the Package Development and Innovation course and the Capstone Research course of BS Packaging Engineering. The teams mostly used ASTM standards, which accounted for 13 standards (68.4%). Two standards (10.5%) that are non-ASTM, such as TAPPI or ISO, were also used. Meanwhile, 4 standards (21.1%), both ASTM and non-ASTM, could not be implemented due to limitations such as resource constraints, equipment availability, or feasibility issues. This distribution shows the predominance of ASTM standards usage in the research related projects, while also noting the minor use of alternative international standards and other constraints that limited the use of other standards.

SUMMARY TABLE OF STANDARDS USED (ALL TEAMS)





REFLECTION

This semester, five webinars were conducted to raise awareness about several ASTM subcommittees, each of which play an important role in upholding the standards that guide various industries. These sessions gave students the opportunity to learn about standards that go beyond those typically covered in our lectures and laboratory activities. While we regularly use ASTM standards during classroom discussions and hands-on experiments, the webinars allowed us to explore new areas and applications we haven't encountered before. Many of us were genuinely curious and eager to learn more, as shown by the active participation and thoughtful questions asked during each Q&A portion. These reflections and interactions showed how the webinars sparked a deeper interest in the broader world of ASTM standards.

FEEDBACK FROM THE STUDENTS

"I liked how the speakers explained technical standards in simple words and showed real packaging applications. It made me feel more prepared for actual OJT in the future." — Julian Garcia

"The presentations were informative and showed how standards affect packaging design and testing. I hope we can have more seminars like this because it really helps us prepare for our future as packaging engineers." — **Joemel Tortosa**

"The topics were very informative and related to what we do in our lecture classes. It helped me understand why we use ASTM methods for our lab experiments." — **Heart Borja**

"I found the presentations helpful because they explained various ASTM standards when testing packaging materials like corrugated boards and plastics, and other packaging materials. It made me realize that without standards, packaging tests won't be consistent. This knowledge is important for us as future packaging engineers." — **Kristine Lumaban**



WORDS OF GRATITUDE FROM THE PRESIDENT

As the president of both the ASTM-CPU Student Chapter and IoPP-CPU Student Chapter, I would like to express my deepest gratitude to the members of ASTM International for the invaluable seminars you conducted, which greatly enriched our knowledge and understanding as future packaging engineers. Special mention to Bryan Williams, Henk Blom, Orthey Scott, and Travis Murdock for making our communication open, meaningful, and accessible despite the significant time zone differences. Your dedication and willingness to share your expertise made each session not only informative but also truly inspiring. Through these seminars, we came to understand how ASTM standards ensure the four main functions of packaging – containment, protection, communication, and utility – are fulfilled with excellence, safety, and consistency in every package we design and test. As student leaders and members of these two organizations, we are reminded that standards connect us globally and strengthen our commitment to our profession. We look forward to more collaborations with you in the future, as each interaction fuels our passion to uphold packaging with integrity and purpose. Thank you for believing in us and for making us feel that even as students here in the Philippines, we are part of a global community working towards safer, stronger, and better packaging for the world. Together, as proud IoPP members and ASTM-CPU student leaders, we will continue to remember that we are united in creating meaningful impact for society through packaging.

